

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2856518

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JORDAN ASHER KATINE	05/07/2014
STEFAN MAAT	05/01/2014
NEIL SMITH	05/01/2014
ALEXANDER M ZELTSER	05/01/2014
HOWARD GORDON ZOLLA	05/01/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HGST NETHERLANDS B.V.
<b>Street Address:</b>	Herikerbergweg 238, Luna Arena
<b>City:</b>	1101 CM AMSTERDAM
<b>State/Country:</b>	NETHERLANDS
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14277978
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(408)717-9155
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	tom.berthold@comcast.net
<b>Correspondent Name:</b>	HGST, A WESTERN DIGITAL COMPANY
<b>Address Line 1:</b>	5600 COTTLE ROAD
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95193
<b>ATTORNEY DOCKET NUMBER:</b>	H20141005US1
<b>NAME OF SUBMITTER:</b>	THOMAS R. BERTHOLD
<b>SIGNATURE:</b>	/Thomas R. Berthold/
<b>DATE SIGNED:</b>	05/15/2014
<b>Total Attachments: 4</b>	
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## ASSIGNMENT FOR PATENT APPLICATION

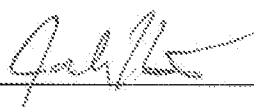
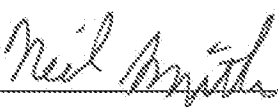
Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

CURRENT-PERPENDICULAR-TO-THE-PLANE (CPP) MAGNETORESISTIVE (MR) SENSOR  
STRUCTURE WITH MULTIPLE STACKED SENSORS AND IMPROVED CENTER SHIELD

Whereas, **HGST Netherlands B.V.**, having a place of business at Herikerbergweg 238, Luna ArenA, 1101 CM Amsterdam, The Netherlands (hereinafter referred to as "HGST"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HGST, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HGST, its successors and assigns; and we hereby agree that HGST may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HGST.

Signed on the date(s) indicated beside my (our) signature(s).

1.	Full Name	Jordan Asher Katine
	Inventor's Signature	 date 5/7/14
2.	Full Name	Stefan Maat
	Inventor's Signature	date
3.	Full Name	Neil Smith
	Inventor's Signature	 date 5/1/14
4.	Full Name	Alexander M. Zeltser
	Inventor's Signature	date

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Inventor's Signature		date
4.	Full Name	Alexander M. Zeltser
Inventor's Signature		date 5/1/14

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5.	Full Name	Howard Gordon Zolla	
	Inventor's Signature	<i>Howard Gordon Zolla</i>	date 5/1/14
6.	Full Name		
	Inventor's Signature		date
7.	Full Name		
	Inventor's Signature		date
8.	Full Name		
	Inventor's Signature		date

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